74LVC14A

Hex inverting Schmitt trigger with 5 V tolerant input

Rev. 6 — 10 June 2016 Product data sheet

1. General description

The 74LVC14A provides six inverting buffers with Schmitt trigger input. It is capable of transforming slowly-changing input signals into sharply defined, jitter-free output signals.

The inputs switch at different points for positive and negative-going signals. The difference between the positive voltage V_{T+} and the negative voltage V_{T-} is defined as the input hysteresis voltage V_H.

Inputs can be driven from either 3.3 V or 5 V devices. This feature allows the use of this device as a translator in mixed 3.3 V and 5 V applications.

2. Features and benefits

- Wide supply voltage range from 1.2 V to 3.6 V
- 5 V tolerant input for interfacing with 5 V logic
- CMOS low-power consumption
- Direct interface with TTL levels
- Unlimited input rise and fall times
- Inputs accept voltages up to 5.5 V
- Complies with JEDEC standard JESD8-C/JESD36 (2.7 V to 3.6 V)
- ESD protection:
  - HBM JESD22-A114F exceeds 2000 V
  - MM JESD22-A115-B exceeds 200 V
  - CDM JESD22-C101E exceeds 1000 V
- Multiple package options
- Specified from –40 °C to +85 °C and from –40 °C to +125 °C

3. Applications

- Wave and pulse shapers for highly noisy environments
- Astable multivibrators
- Monostable multivibrators

4. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74LVC14AD	–40 °C to +125 °C	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1
74LVC14ADB	–40 °C to +125 °C	SSOP14	plastic thin shrink small outline package; 14 leads; body width 5.3 mm	SOT337-1
74LVC14APW	–40 °C to +125 °C	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1
74LVC14ABQ	–40 °C to +125 °C	DHVQFN14	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 × 3 × 0.85 mm	SOT762-1

5. Functional diagram

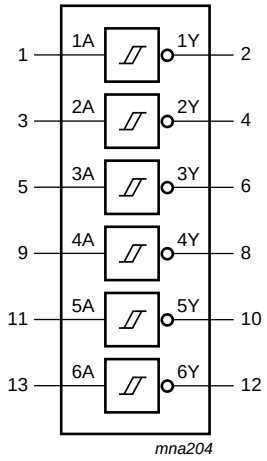


Fig 1. Logic symbol

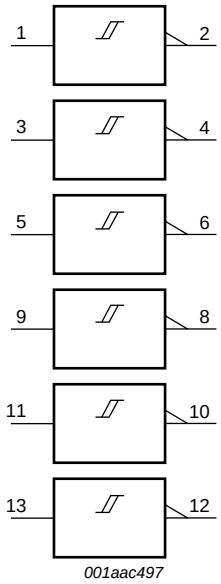


Fig 2. IEC logic symbol

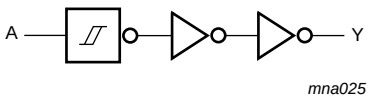


Fig 3. Logic diagram for one Schmitt trigger

6. Pinning information

6.1 Pinning

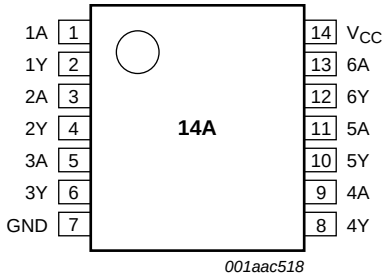
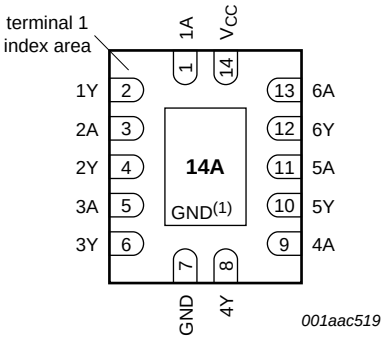


Fig 4. Pin configuration SO14, SSOP14 and TSSOP14



Transparent top view

(1) This is not a supply pin. The substrate is attached to this pad using conductive die attach material. There is no electrical or mechanical requirement to solder this pad. However, if it is soldered, the solder land should remain floating or be connected to GND.

Fig 5. Pin configuration DHVQFN14

6.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1A, 2A, 3A, 4A, 5A, 6A	1, 3, 5, 9, 11, 13	data input
1Y, 2Y, 3Y, 4Y, 5Y, 6Y	2, 4, 6, 8, 10, 12	data output
GND	7	ground (0 V)
V_{CC}	14	supply voltage

7. Functional description

Table 3. Function table[1]

Input nA	Output nY
L	H
H	L

[1] H = HIGH voltage level; L = LOW voltage level

8. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{CC}	supply voltage			−0.5	+6.5	V
V_I	input voltage		[1]	−0.5	+6.5	V
V_O	output voltage		[2]	−0.5	V_{CC} + 0.5	V
I_{IK}	input clamping current	V_I < 0 V		−50	-	mA
I_{OK}	output clamping current	V_O > V_{CC} or V_O < 0 V		-	±50	mA
I_O	output current	V_O = 0 V to V_{CC}		-	±50	mA
I_{CC}	supply current			-	100	mA
I_{GND}	ground current			−100	-	mA
T_{stg}	storage temperature			−65	+150	°C
P_{tot}	total power dissipation	T_{amb} = −40 °C to +125 °C	[3]	-	500	mW

[1] The minimum input voltage ratings may be exceeded if the input current ratings are observed.

[2] The output voltage ratings may be exceeded if the output current ratings are observed.

[3] For SO14 packages: P_{tot} derates linearly with 8 mW/K above 70 °C.
For (T)SSOP14 packages: P_{tot} derates linearly with 5.5 mW/K above 60 °C.
For DHVQFN14 packages: P_{tot} derates linearly with 4.5 mW/K above 60 °C.

9. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{CC}	supply voltage			1.65	-	3.6	V
		functional		1.2	-	-	V
V_I	input voltage			0	-	5.5	V
V_O	output voltage			0	-	V_{CC}	V
T_{amb}	ambient temperature			−40	-	+125	°C

10. Static characteristics

Table 6. Static characteristics

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		–40 °C to +85 °C			–40 °C to +125 °C		Unit
				Min	Typ[1]	Max	Min	Max	
V_{OH}	HIGH-level output voltage	$V_I = V_{T+}$ or V_{T-}							
		I_O = –100 μA; V_{CC} = 1.65 V to 3.6 V		V_{CC} – 0.2	-	-	V_{CC} – 0.3	-	V
		I_O = –4 mA; V_{CC} = 1.65 V		1.2	-	-	1.05	-	V
		I_O = –8 mA; V_{CC} = 2.3 V		1.8	-	-	1.65	-	V
		I_O = –12 mA; V_{CC} = 2.7 V		2.2	-	-	2.05	-	V
		I_O = –18 mA; V_{CC} = 3.0 V		2.4	-	-	2.25	-	V
		I_O = –24 mA; V_{CC} = 3.0 V		2.2	-	-	2.0	-	V
V_{OL}	LOW-level voltage output	$V_I = V_{T+}$ or V_{T-}							
		I_O = 100 μA; V_{CC} = 1.65 V to 3.6 V		-	-	0.2	-	0.3	V
		I_O = 4 mA; V_{CC} = 1.65 V		-	-	0.45	-	0.65	V
		I_O = 8 mA; V_{CC} = 2.3 V		-	-	0.6	-	0.8	V
		I_O = 12 mA; V_{CC} = 2.7 V		-	-	0.4	-	0.6	V
		I_O = 24 mA; V_{CC} = 3.0 V		-	-	0.55	-	0.8	V
I_I	input leakage current	V_{CC} = 3.6 V; V_I = 5.5 V or GND		-	±0.1	±5	-	±20	μA
I_{CC}	supply current	V_{CC} = 3.6 V; V_I = V_{CC} or GND; I_O = 0 A		-	0.1	10	-	40	μA
ΔI_{CC}	additional supply current	per input pin; V_{CC} = 2.7 V to 3.6 V; V_I = V_{CC} – 0.6 V; I_O = 0 A		-	5	500	-	5000	μA
C_I	input capacitance	V_{CC} = 0 V to 3.6 V; V_I = GND to V_{CC}		-	4.0	-	-	-	pF

[1] All typical values are measured at V_{CC} = 3.3 V (unless stated otherwise) and T_{amb} = 25 °C.

11. Dynamic characteristics

Table 7. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V). For test circuit see Figure 7.

Symbol	Parameter	Conditions		–40 °C to +85 °C			–40 °C to +125 °C		Unit
				Min	Typ[1]	Max	Min	Max	
t_{pd}	propagation delay	nA to nY; see Figure 6	[2]						
		V_{CC} = 1.2 V		-	16	-	-	-	ns
		V_{CC} = 1.65 V to 1.95 V		1.0	6.1	12.7	1.0	14.7	ns
		V_{CC} = 2.3 V to 2.7 V		1.5	3.5	7.8	1.5	10.0	ns
		V_{CC} = 2.7 V		1.5	3.6	7.5	1.5	9.5	ns
		V_{CC} = 3.0 V to 3.6 V		1.0	3.2	6.4	1.0	8.0	ns
$t_{sk(o)}$	output skew time	V_{CC} = 3.0 V to 3.6 V	[3]	-	-	1.0	-	1.5	ns

Table 7. Dynamic characteristics *...continued*

Voltages are referenced to GND (ground = 0 V). For test circuit see Figure 7.

Symbol	Parameter	Conditions		–40 °C to +85 °C			–40 °C to +125 °C		Unit
				Min	Typ[1]	Max	Min	Max	
C_{PD}	power dissipation capacitance	per buffer; V_I = GND to V_{CC}	[4]						
		V_{CC} = 1.65 V to 1.95 V		-	9.0	-	-	-	pF
		V_{CC} = 2.3 V to 2.7 V		-	12.5	-	-	-	pF
		V_{CC} = 3.0 V to 3.6 V		-	15.6	-	-	-	pF

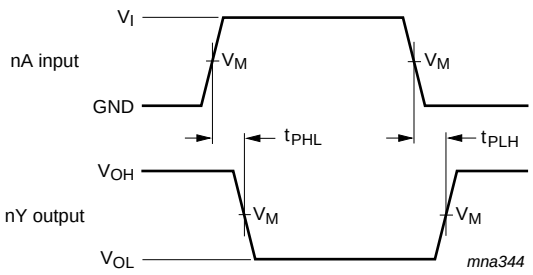
[1] Typical values are measured at T_{amb} = 25 °C and V_{CC} = 1.2 V, 1.8 V, 2.5 V, 2.7 V, and 3.3 V respectively.

[2] t_{pd} is the same as t_{PLH} and t_{PHL}.

[3] Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.

[4] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).
$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:
f_i = input frequency in MHz; f_o = output frequency in MHz
C_L = output load capacitance in pF
V_{CC} = supply voltage in Volts
N = number of inputs switching
$\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

12. Waveforms

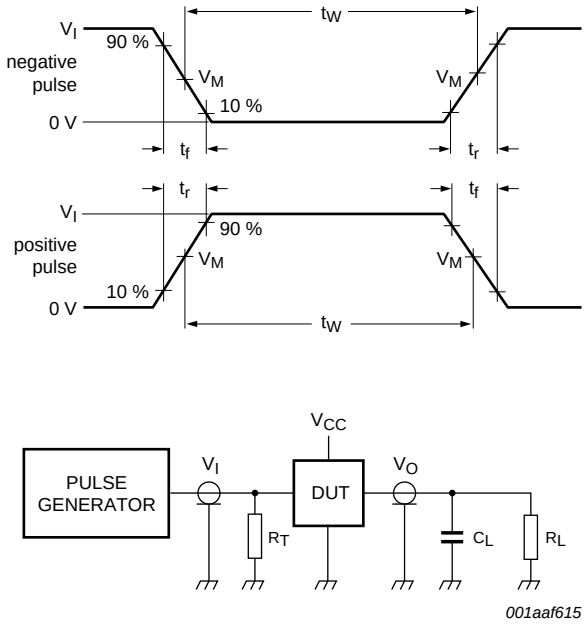


V_M = 1.5 V at $V_{CC} \geq$ 2.7 V

V_M = 0.5 × V_{CC} at V_{CC} < 2.7 V.

V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 6. Propagation delay input (nA) to output (nY)



Test data is given in Table 8. Definitions for test circuit:

R_L = Load resistance

C_L = Load capacitance including jig and probe capacitance

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

Fig 7. Load circuitry for measuring switching times

Table 8. Test data

Supply voltage	Input		Load	
	V_I	t_r, t_f	C_L	R_L
1.2 V	V_{CC}	≤ 2 ns	30 pF	1 kΩ
1.65 V to 1.95 V	V_{CC}	≤ 2 ns	30 pF	1 kΩ
2.3 V to 2.7 V	V_{CC}	≤ 2 ns	30 pF	500 Ω
2.7 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω
3.0 V to 3.6 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω

13. Transfer characteristics

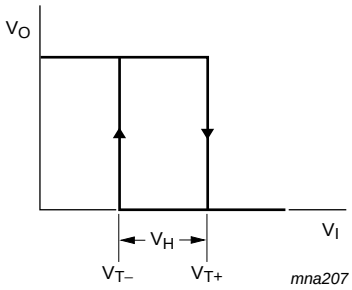
Table 9. Transfer characteristics

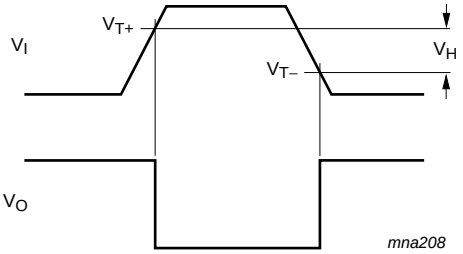
Voltages are referenced to GND (ground = 0 V); see Figure 8.

Symbol	Parameter	Conditions		T_{amb} = –40 °C to +85 °C		T_{amb} = –40 °C to +125 °C		Unit
				Min	Max	Min	Max	
V_{T+}	positive-going threshold voltage	V_{CC} = 1.2 V		0.2	1.0	0.2	1.0	V
		V_{CC} = 1.65 V		0.4	1.3	0.4	1.3	V
		V_{CC} = 1.95 V		0.6	1.5	0.6	1.5	V
		V_{CC} = 2.3 V		0.8	1.7	0.8	1.7	V
		V_{CC} = 2.5 V		0.9	1.7	0.9	1.7	V
		V_{CC} = 2.7 V		1.1	2	1.1	2	V
		V_{CC} = 3 V		1.2	2	1.2	2	V
		V_{CC} = 3.6 V		1.2	2	1.2	2	V
V_{T-}	negative-going threshold voltage	V_{CC} = 1.2 V		0.12	0.75	0.12	0.75	V
		V_{CC} = 1.65 V		0.15	0.85	0.15	0.85	V
		V_{CC} = 1.95 V		0.25	0.95	0.25	0.95	V
		V_{CC} = 2.3 V		0.4	1.1	0.4	1.1	V
		V_{CC} = 2.5 V		0.4	1.2	0.4	1.2	V
		V_{CC} = 2.7 V		0.8	1.4	0.8	1.4	V
		V_{CC} = 3 V		0.8	1.5	0.8	1.5	V
		V_{CC} = 3.6 V		0.8	1.5	0.8	1.5	V
V_H	hysteresis voltage ($V_{T+} - V_{T-}$)	V_{CC} = 1.2 V		0.1	1.0	0.1	1.0	V
		V_{CC} = 1.65 V		0.2	1.15	0.2	1.15	V
		V_{CC} = 1.95 V		0.2	1.25	0.2	1.25	V
		V_{CC} = 2.3 V		0.3	1.3	0.3	1.3	V
		V_{CC} = 2.5 V		0.3	1.3	0.3	1.3	V
		V_{CC} = 2.7 V		0.3	1.1	0.3	1.1	V
		V_{CC} = 3 V		0.3	1.2	0.3	1.2	V
		V_{CC} = 3.6 V	[1]	0.3	1.2	0.3	1.2	V

[1] Typical transfer characteristic is displayed in Figure 9.

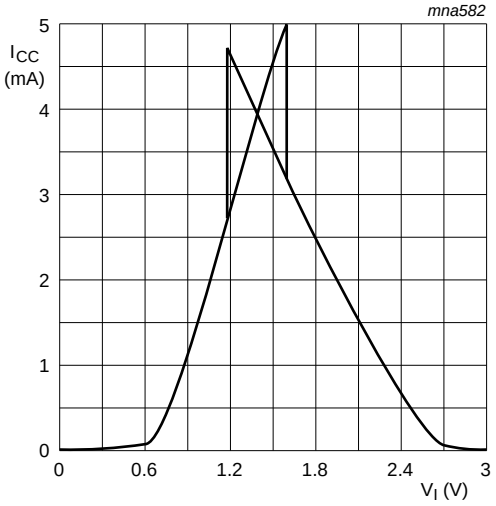
14. Waveforms transfer characteristics





V_{T-} at 20 % and V_{T+} at 70 %

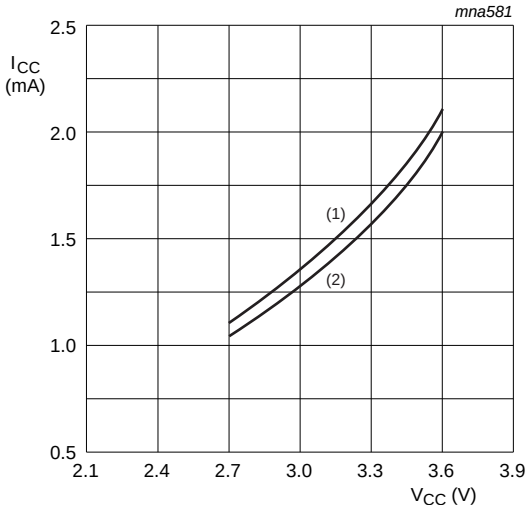
Fig 8. Definition of V_{T+}, V_{T-} and V_H



V_{CC} = 3.3 V.

Fig 9. Typical transfer characteristic

15. Application information



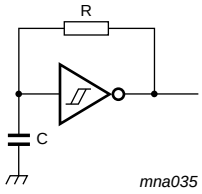
(1) Positive-going edge.

(2) Negative going-edge.

Linear change of V_I between 0.8 V to 2.0 V.

All values given are typical unless otherwise specified.

Fig 10. Average supply current as a function of supply voltage

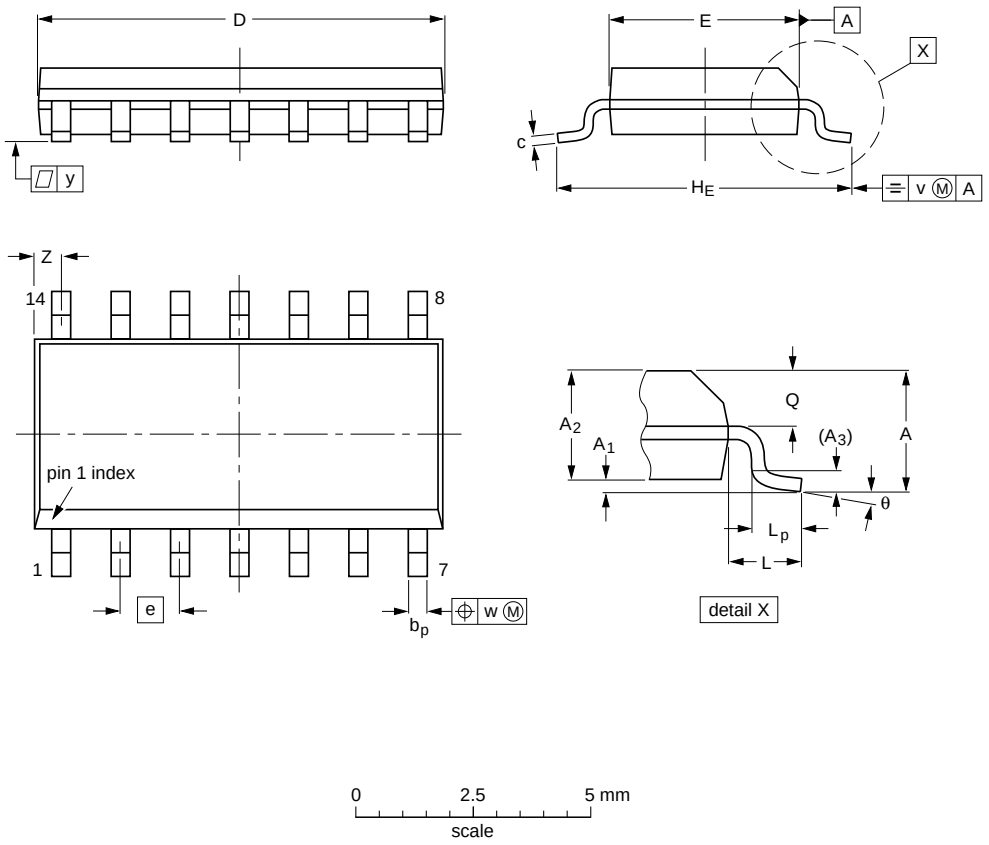


$$f = \frac{1}{T} \approx \frac{1}{0.8 \times RC}$$ at V_{CC} = 3.0 V

Fig 11. Relaxation oscillator

16. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm **SOT108-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8^o 0^o
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.35 0.34	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

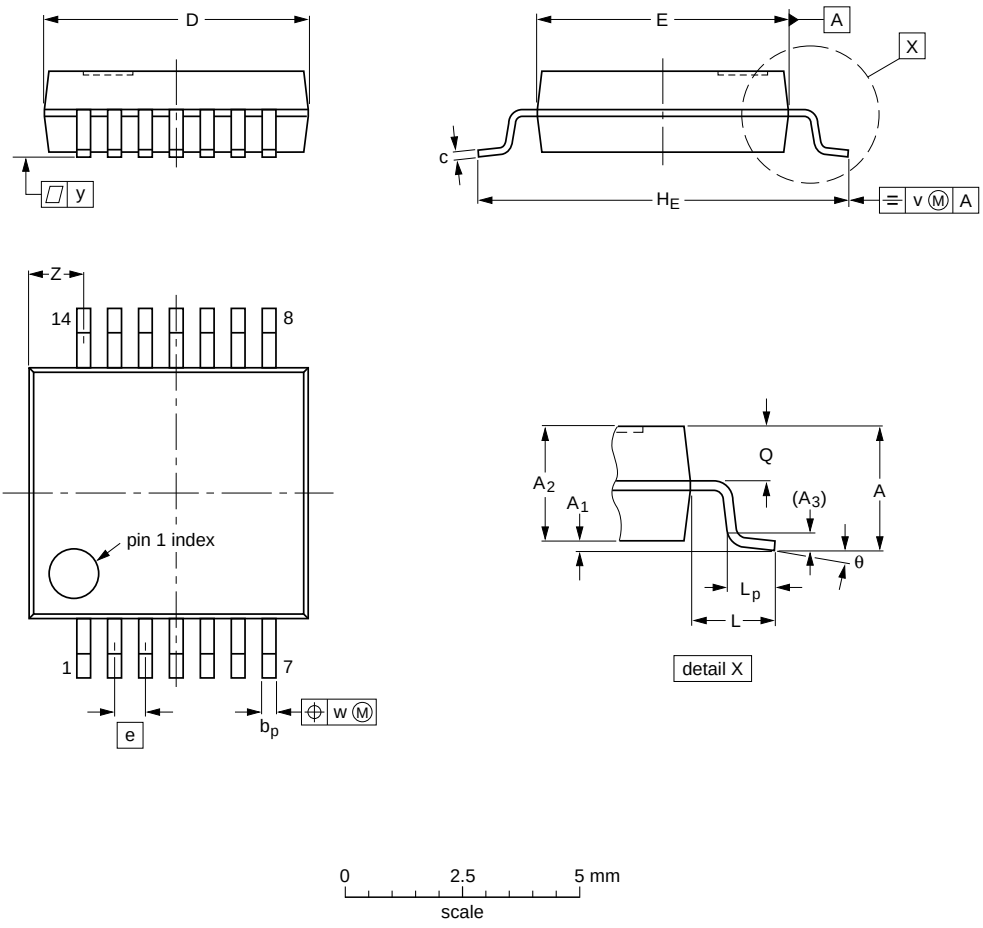
Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT108-1	076E06	MS-012				~~99-12-27~~ 03-02-19

Fig 12. Package outline SOT108-1 (SO14)

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm **SOT337-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (1)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	2	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.4 0.9	8^o 0^o

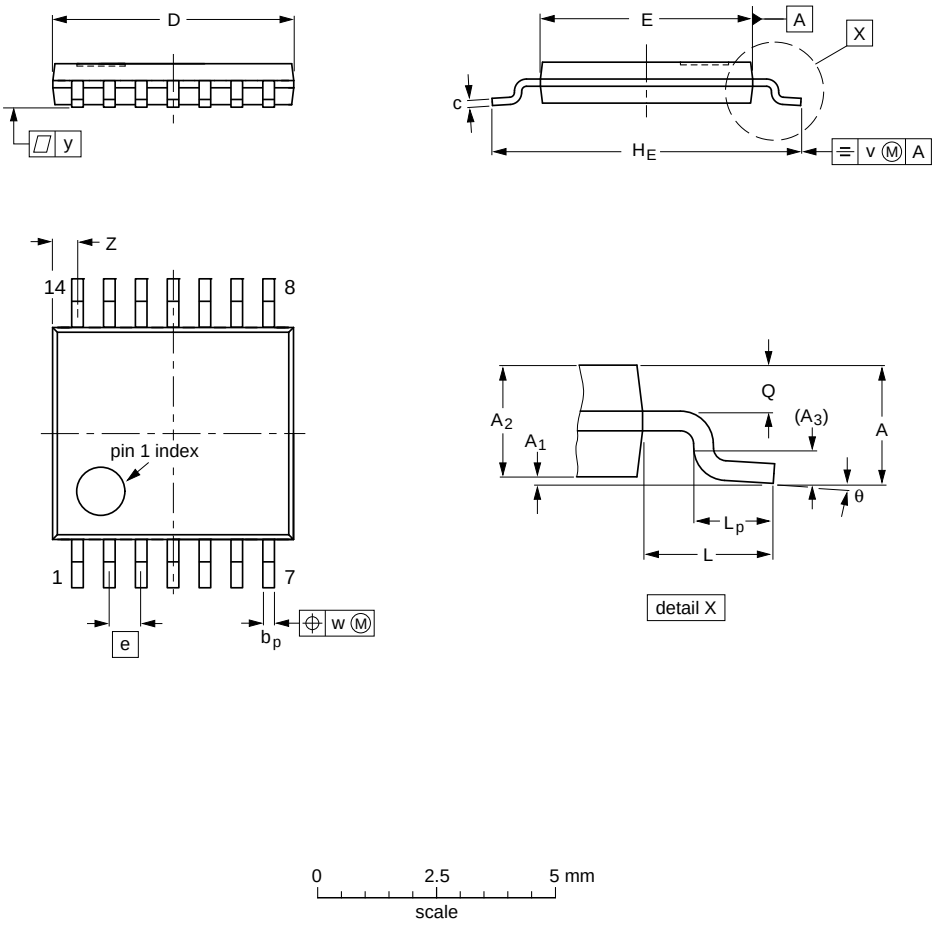
Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT337-1		MO-150				~~99-12-27~~ 03-02-19

Fig 13. Package outline SOT337-1 (SSOP14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm **SOT402-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8^o 0^o

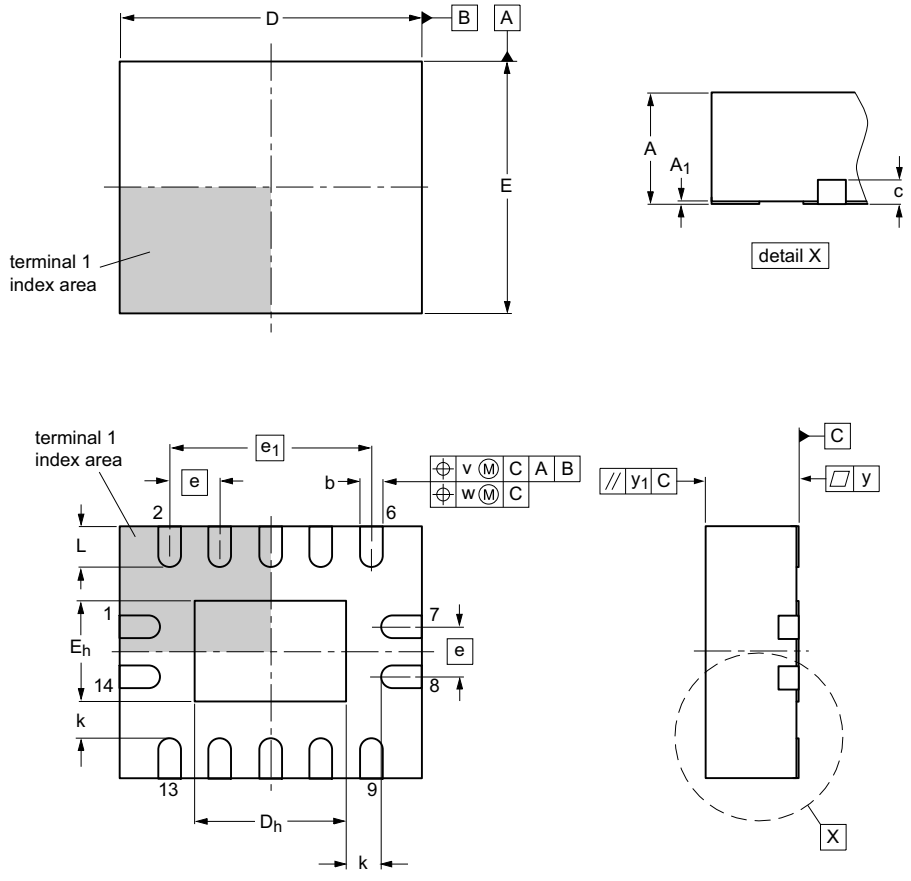
Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT402-1		MO-153				~~99-12-27~~ 03-02-18

Fig 14. Package outline SOT402-1 (TSSOP14)

DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm **SOT762-1**



Dimensions (mm are the original dimensions)

Unit		$A^{(1)}$	A_1	b	c	$D^{(1)}$	D_h	$E^{(1)}$	E_h	e	e_1	k	L	v	w	y	y_1
	max	1	0.05	0.30		3.1	1.65	2.6	1.15				0.5				
mm	nom		0.02	0.25	0.2	3.0	1.50	2.5	1.00	0.5	2		0.4	0.1	0.05	0.05	0.1
	min		0.00	0.18		2.9	1.35	2.4	0.85			0.2	0.3				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot762-1_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT762-1		MO-241				~~15-04-10~~ 15-05-05

Fig 15. Package outline SOT762-1 (DHVQFN14)

17. Abbreviations

Table 10. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

18. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC14A v.6	20160610	Product data sheet	-	74LVC14A v.5
Modifications:	• Table 4: table note removed (errata).			
74LVC14A v.5	20111223	Product data sheet	-	74LVC14A v.4
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Table 4, Table 5, Table 6, Table 7 and Table 8: values added for lower voltage ranges.			
74LVC14A v.4	20050215	Product data sheet	-	74LVC14A v.3
74LVC14A v.3	20030228	Product specification	-	74LVC14A v.2
74LVC14A v.2	20020315	Product specification	-	74LVC14A v.1
74LVC14A v.1	19980428	Product specification		-

19. Legal information

19.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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21. Contents

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Date of release: 10 June 2016
Document identifier: 74LVC14A